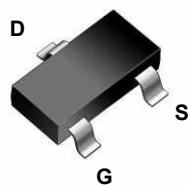
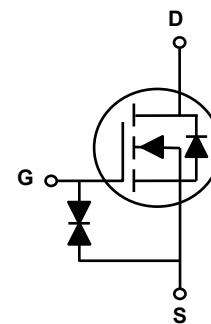


Main Product Characteristics

$V_{(BR)DSS}$	20V
$R_{DS(ON)}$	300mΩ
I_D	800mA



SOT-523



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery
- ESD level: 2kV



Description

The SSF2320Y utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Drain Current-Continuous ($T_C=25^\circ\text{C}$)	I_D	800	mA
Drain Current-Continuous ($T_C=100^\circ\text{C}$)		510	
Drain Current-Pulsed ¹	I_{DM}	3.2	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	312	mW
Power Dissipation - Derate above 25°C		2.5	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	400	°C/W
Operating Junction Temperature Range	T_J	-55 To +150	°C
Storage Temperature Range	T_{STG}	-55 To +150	°C

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	-	-0.01	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{DS}}=16\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 6\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 20	μA
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0.5\text{A}$	-	200	300	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=0.4\text{A}$	-	235	400	
		$V_{\text{GS}}=1.8\text{V}, I_{\text{D}}=0.2\text{A}$	-	295	550	
		$V_{\text{GS}}=1.5\text{V}, I_{\text{D}}=0.1\text{A}$	-	365	800	
		$V_{\text{GS}}=1.2\text{V}, I_{\text{D}}=0.1\text{A}$	-	600	1500	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	0.3	0.6	1	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	3	-	$\text{mV}/^\circ\text{C}$
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q_g	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=0.5\text{A}$ $V_{\text{GS}}=4.5\text{V}$	-	1	2	nC
Gate-Source Charge ^{2,3}	Q_{gs}		-	0.26	0.5	
Gate-Drain Charge ^{2,3}	Q_{gd}		-	0.2	0.4	
Turn-On Delay Time ^{2,3}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=10\text{V}, R_{\text{G}}=10\Omega$ $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0.5\text{A}$	-	5	10	nS
Rise Time ^{2,3}	t_r		-	3.5	7	
Turn-Off Delay Time ^{2,3}	$t_{\text{d}(\text{off})}$		-	14	28	
Fall Time ^{2,3}	t_f		-	6	12	
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	38.2	75	pF
Output Capacitance	C_{oss}		-	14.4	28	
Reverse Transfer Capacitance	C_{rss}		-	6	12	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	-	-	0.8	A
Pulsed Source Current	I_{SM}		-	-	1.6	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_s=0.2\text{A}, T_J=25^\circ\text{C}$	-	-	1	V

Note:

- Repetitive Rating: Pulsed width limited by maximum junction temperature.
- The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

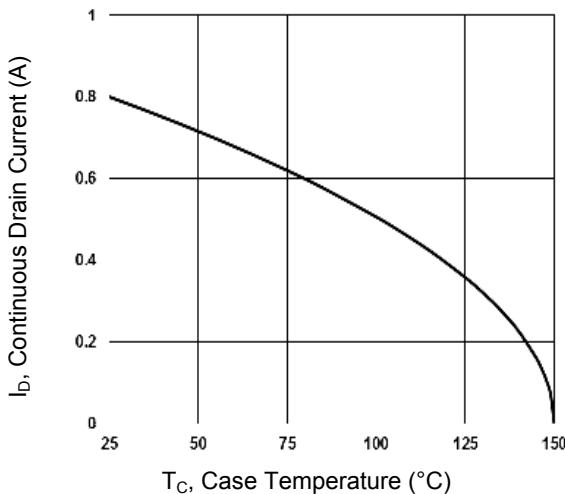


Figure 1. Continuous Drain Current vs. T_c

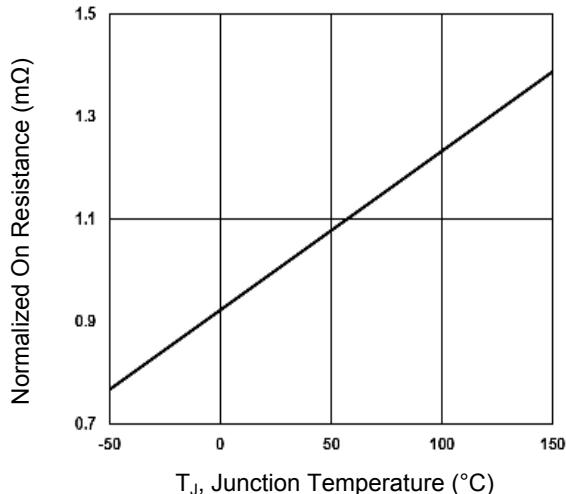


Figure 2. Normalized $R_{D_s(\text{ON})}$ vs. T_j

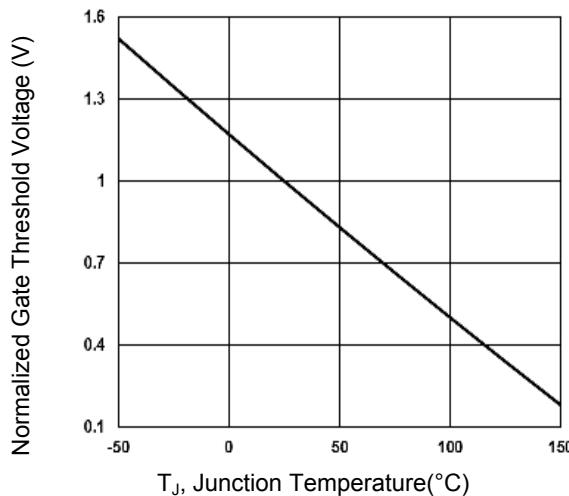


Figure 3. Normalized V_{th} vs T_j

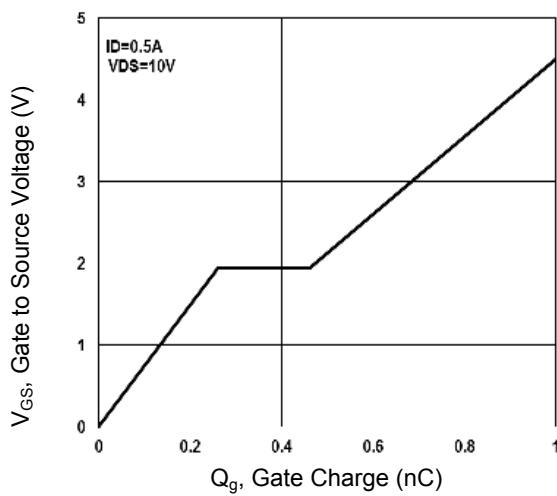


Figure 4. Gate Charge Waveform

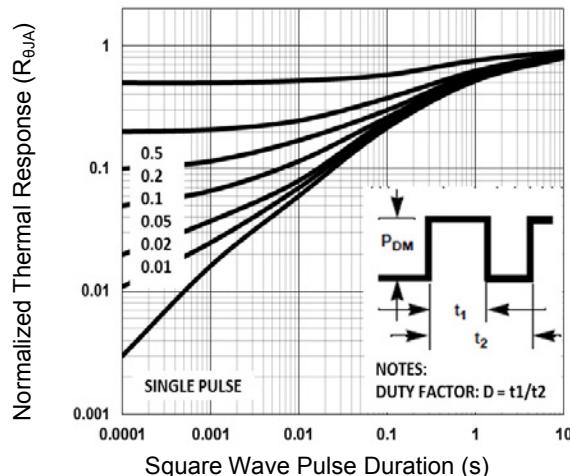


Figure 5. Normalized Transient Impedance

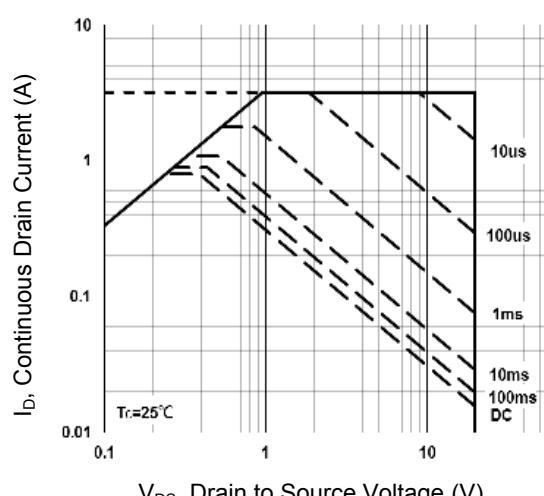


Figure 6. Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

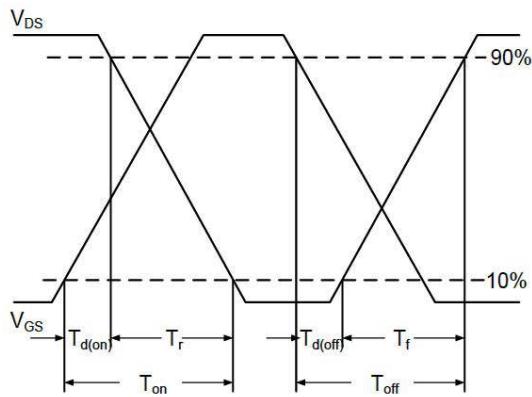


Figure 7. Switching Time Waveform

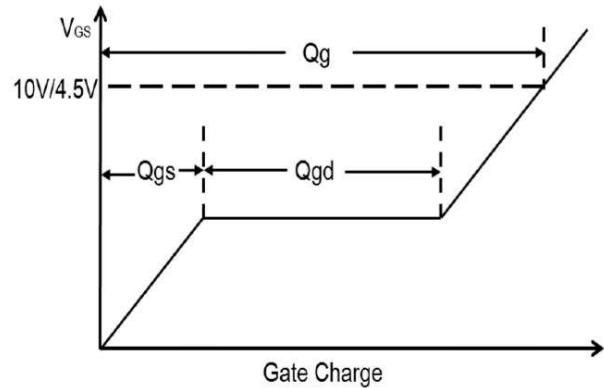
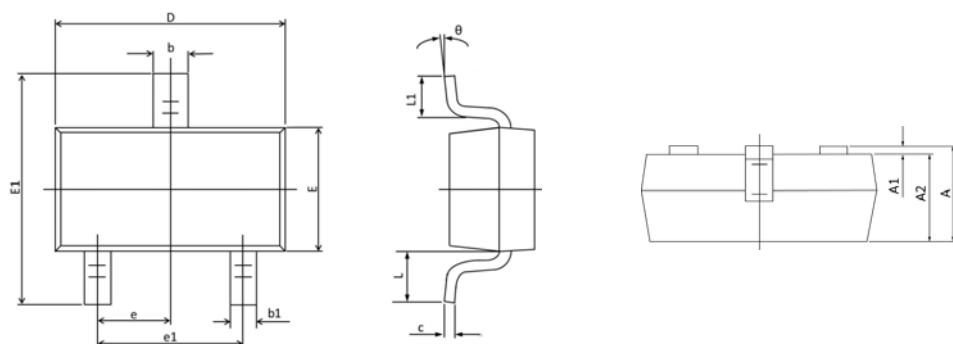


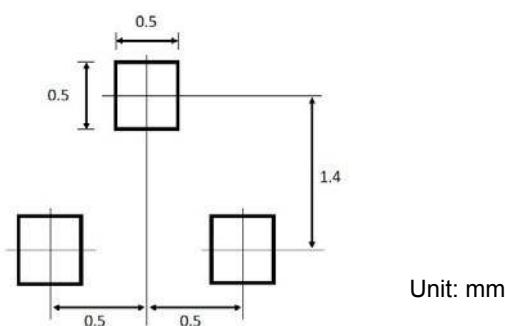
Figure 8. Gate Charge Waveform

Package Outline Dimensions (SOT-523)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.014
b1	0.150	0.250	0.006	0.010
c	0.100	0.200	0.004	0.008
D	1.500	1.750	0.059	0.069
E	0.700	0.900	0.028	0.035
E1	1.400	1.750	0.055	0.069
e	0.500 TYP		0.020 TYP	
e1	0.900	1.100	0.035	0.043
L	0.300	0.460	0.012	0.018
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Recommended Pad Layout



Order Information

Device	Package	Marking	Carrier	Quantity
SSF2320Y	SOT-523	B	Tape & Reel	3,000 pcs / Reel